L Number	Hits	Search Text	DB	Time stamp
1	3973	324/765-769.ccls.	USPAT;	2002/07/24 11:43
			US-PGPUB;	
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	269	324/765-769.ccls. and spring	USPAT;	2002/07/24 11:43
			US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	199	(324/765-769.ccls. and spring) and (ball bead bump lead)	USPAT;	2002/07/24 11:44
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	7542	(ball bump bead) near8 (contact\$3 connect\$3) near8 spring	USPAT;	2002/07/24 13:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
29	127	((ball bump bead) near8 (contact\$3 connect\$3) near8 spring)	USPAT;	2002/07/24 13:33
23	'-'	and BGA	US-PGPUB:	
			EPO; JPO;	
		*	DERWENT;	
	i .		IBM_TDB	
36	2230	(ball bump bead) near3 (contact\$3 connect\$3) near3 spring	USPAT;	2002/07/24 14:53
30	2230	(ball bullip bead) ficale (corrected corrected) ficale opining	US-PGPUB;	2002077211100
			EPO; JPO;	
İ			DERWENT;	
			IBM_TDB	
43	270338	(opening hole via socket) near20 spring	USPAT;	2002/07/24 14:17
43	270330	(opening note via socket) hearzo spring	US-PGPUB;	2002/07/21 11:17
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
50	945	((ball bump bead) near3 (contact\$3 connect\$3) near3 spring)	USPAT;	2002/07/24 14:20
30	943	and ((opening hole via socket) near20 spring)	US-PGPUB;	2002/07/24 14.20
		and ((opening note via socker) hearzo spring)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
57	282	((ball bump bead) near3 (contact\$3 connect\$3) near3 spring)	USPAT;	2002/07/24 14:27
57	202	near20 (portion part)	US-PGPUB;	2302101127 17.21
		nearzo (portion part)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
64	24	(((ball bump bead) near3 (contact\$3 connect\$3) near3	USPAT;	2002/07/24 14:28
04	24	spring) and ((opening hole via socket) near20 spring)) and	US-PGPUB:	
į		spring) and ((opening note via socker) hearzo spring)) and bga	EPO; JPO;	
		nga .	DERWENT;	
			IBM_TDB	
71	430	(ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	USPAT;	2002/07/24 14:55
71	430	helix helical spiral)	US-PGPUB;	2302/01/27 17.00
		Helix Helical Spiral)	EPO; JPO;	
			DERWENT;	
		•		
70	_	(/hall human hand) moor? (contact@? connect@?) moor? (coil	IBM_TDB USPAT;	2002/07/24 15:54
78	8	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	1 '	2002/01/24 10.04
		helix helical spiral)) and bga	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

85	3	5854558.pn.	USPAT;	2002/07/24 14:57
65		3004030.pn:	US-PGPUB;	2002.0172111.07
			EPO; JPO;	
1		•	DERWENT;	
			IBM TDB	
00	١	6220220 mm	USPAT;	2002/07/24 14:58
92	2	6229320.pn.	US-PGPUB;	2002/07/24 14.50
			EPO; JPO;	
			DERWENT;	
	}		IBM_TDB	
	11947	fill\$3 near3 (hole via groove socket) near10 (conduct\$3)	USPAT;	2002/07/24 16:26
99	11947	I III \$5 Hears (Hole via groove socker) hear to (conductos)	US-PGPUB;	2002/01/24 10.20
			EPO; JPO;	
		<u> </u>		
		-	DERWENT;	
	400	// · · · · · · · · · · · · · · · · · ·	IBM_TDB	2002/07/04 46:42
106	169	((opening hole via socket) near20 spring) and (fill\$3 near3	USPAT;	2002/07/24 16:13
		(hole via groove socket) near10 (conduct\$3))	US-PGPUB;	
			EPO; JPO;	
İ			DERWENT;	
		(51100 - 10	IBM_TDB	0000/07/04 40:44
113	23	((opening hole via socket) near20 spring) same (fill\$3 near3	USPAT;	2002/07/24 16:11
		(hole via groove socket) near10 (conduct\$3))	US-PGPUB;	
			EPO; JPO;	
		^	DERWENT;	
	_		IBM_TDB	0000/07/04 40:40
120	0	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	USPAT;	2002/07/24 16:12
		helix helical spiral)) same (fill\$3 near3 (hole via groove	US-PGPUB;	
		socket) near10 (conduct\$3))	EPO; JPO;	
			DERWENT;	,
		(44 H)	IBM_TDB	0000/07/04 46:40
127	1	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	USPAT;	2002/07/24 16:12
		helix helical spiral)) and (fill\$3 near3 (hole via groove socket)	US-PGPUB;	
		near10 (conduct\$3))	EPO; JPO;	
		•	DERWENT;	
1.04	-	///	IBM_TDB	2002/07/24 16:15
134	29	(((opening hole via socket) near20 spring) and (fill\$3 near3	USPAT; US-PGPUB:	2002/07/24 16:15
		(hole via groove socket) near10 (conduct\$3))) and (PCB		
	İ	PWB BGA)	EPO; JPO;	
			DERWENT;	
144		5 366 390 pp	IBM_TDB	2002/07/24 16:15
141	3	5,366,380.pn.	USPAT;	2002/01/24 10.15
			US-PGPUB;	
			EPO; JPO; DERWENT;	
		,	IBM TDB	
140	404	(hala via menava anakat) maar10 (aamatust02 aaldar maata)	_	2002/07/24 16:56
148	161	(hole via groove socket) near10 (conduct\$3 solder paste)	USPAT; US-PGPUB;	2002/01/24 10.30
	1	near10 ((hold\$3 bond\$3) near3 (spring coil helix helical	EPO; JPO;	
		spiral))	DERWENT;	
			IBM_TDB	
1	1	1	סטו_ואטו	